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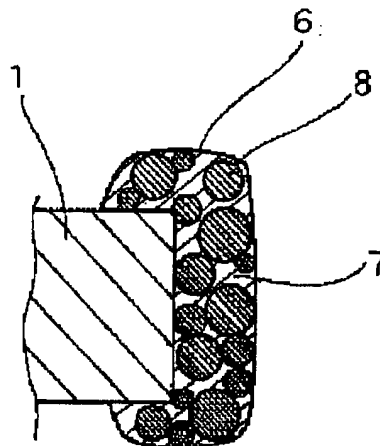
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APPLICANT : ROHM CO LTD;

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TITLE : ELECTRODE MATERIAL AND
CHIPLIKE ELECTRONIC COMPONENT
USING THE SAME



ABSTRACT : PURPOSE: To obtain excellent solderability without forming a plated layer on a surface by forming thermosetting resin of phenol resin or acrylic resin.

CONSTITUTION: An electrode material contain as indispensable ingredients conductive powder 8, thermosetting resin 7 and solvent, and as the resin 7, phenol resin or acrylic resin is used. The blending rate of the resin 7 is about 10 to 30% of the entire weight. Material 1 to be coated is, for example, coated with this material, heated for a predetermined time to cure the resin 7, then returned to the ambient temperature to an electrode layer 6. Thus, solder and side electrode layer can be sufficiently rigidly welded.

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